●**DFN1010-4C(DAF) Power Dissipation (JESD51-7) ※Tjmax=150℃**Power dissipation data for the DFN1010-4C is shown in this page.

The value of power dissipation varies with the mount board conditions. Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions:For a 4-layer PCB measuring 76.2mm x 114.3mm (approximately 8700mm2 on one side)

The copper foil areas are as follows.

1st layer: No copper foil (For signal layer)

2nd layer: 74.2mm x 74.2mm (Connected to heat sink)

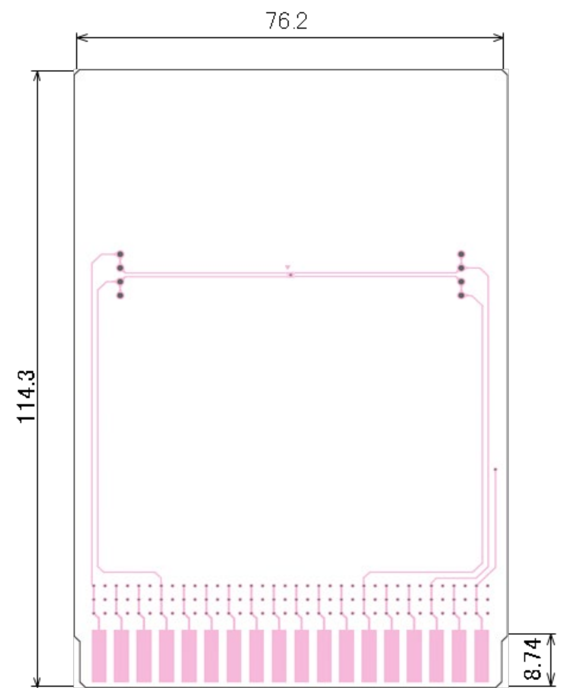
3rd layer: 74.2mm x 74.2mm (not connected to heat sink)

4th layer: No copper foil (For signal layer)

Material: Glass Epoxy (FR-4)

Thickness: 1.6mm

Through-hole:φ0.3mm



Evaluation Board Layout (Unit:mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (Timax=150℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)		Thermal Resistance (℃/W)
	Ta max=125℃	Ta max=150℃	
25	830	830	150.60
125	159	159	
150	0	0